

Bow Electronic Solder Paste Selector Chart

	RA (500 Series)	RMA (700 Series)	Water Soluble (1200 Series)	No Clean (1100 Series)
Low Melt Alloys				Bow NC-1105 (Bi alloys)
				Bow NC-1115LF (Bi alloy back-up)
Tin-Lead		Bow RMA-750	Bow WS-1230 (higher activity version of NC-1150LF)	Bow NC-1150 (biggest seller, washable no clean)
		Bow RMA-760	Bow WS-1250 (2% chloride, tin-lead only)	Bow NC-1125 (Broad latitude, good starting point)
			Bow WS-1250.4 (4% chloride)	Bow NC-1170 (profile forgiving)
			Bow WS-1250.6 (6% chloride similar to Alpha WS609)	
			Bow NC-1150 (washable no clean, CEM)	
Lead-Free	Bow RA-550LF (same as RMA-750LF)	Bow RMA-750LF (Sn/Ag alloys only)	Bow WS-1230 (higher activity version of NC-1150LF)	Bow NC-1150LF (biggest seller, washable no clean)
	Bow RA-560 (More active RMA-760)	Bow RMA-760 (more active RMA-750, SAC alloys, industrial apps too)	Bow WS-1250LF (6% chloride same as WS-1250.6)	Bow NC-1115LF (100% halide free)
			Bow NC-1150LF (washable no clean, CEM)	Bow NC-1125LF (1 st Pb-free, widely accepted, 2 nd choice, favored by memory module mfg.)
High Melt Alloys			Bow WS-1240 (dark residue after reflow, cleans easily)	Bow NC-1175 (higher viscosity, UV tracer, high melt Alloys)

Note: Water Washable No Cleans are unique and can help Contract Electronic Manufactures cut the number of solder paste they use in half. Most shops use a WS Tin-Lead, WS Lead-Free, NC Tin-Lead and NC Lead-Free (total of 4). NC-1150 Tin-Lead and NC1150LF Lead-Free allows them to use 2 paste and water wash when needed. Less scrap and less chance for an operator to use the wrong product (added insurance against mistakes).

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